

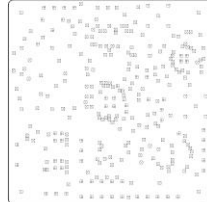
PCB Manufacturing Instructions

Project Name : **240G_002**

Revision : 002

X = 50.8 mm

Y = 50.8 mm



mils	Count
.10	215
.32	62
.60	14
.125	4
Total	295

Fabrication notes 240G_002 Drill Drawing

1. Material, 4 Layer, FR-4 Glass Epoxy Laminate, 1oz copper, 0.8 mm finished thickness.
2. Manufacturing shall meet IPC-A-600 requirements.
3. All plated through holes shall have plating of 0.03 mm minimum.
4. Solder mask on Top and Bottom layers in RED over Bare Copper (SMOBC).
5. All exposed pads to be HOT Air Solder Levelled.
6. NO SILKSCREEN on either side.
7. There shall be no stray metal particles on the PCB or Circuits.
8. ALL Boards shall be electrically tested for opens and shorts.
9. ALL attached drawings are viewed from the Top side view.
10. ALL CAD dimensions are in Inches.
11. Route edge of PCB in accordance with the Mechanical Outline

<u>Layer order</u>	Top Solder Mask
	Top Layer
	FR-4
	Ground Plane
	FR-4
	Mid1 Layer
	FR-4
	Bottom Layer
	Bottom Solder Mask